

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

TOYOSHIMA et al.

Application No.: Unassigned

Art Unit: Unassigned

Filed: December 18, 2000

Examiner: Unassigned

For: METHOD OF PRO-
DUCING A MULTI-
LAYERED WIRING
BOARD

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D. C. 20231

Dear Sir:

Prior to examination, Applicants request that the referenced patent application be amended as shown below.

IN THE SPECIFICATION

- Page 1, line 1, delete entirely;
- line 11, delete "rapidly";
- line 12, delete "the";
- line 14, change "electric" to --electrical--;
- line 16, change "press" to --pressure--;
- line 21, change "by" to --of--;
- line 22, change "generally the" to --, generally, a--;
- Page 2, line 7, delete ", for example";
- line 10, change "photo" to --photolithographic--;
- Page 3, line 1, change "holding electric" to --electrical--;
- line 13, delete "away an";
- line 19, change "structures" to --structure--;
- line 23, delete "away";
- Page 4, line 1, change "is buried into" to --fills--;
- line 3, change "the" to --a--;
- line 4, delete "an";
- delete "applying";

line 5, delete "to";

line 6, delete "growing";

change "on only" to --only on--;

Page 5, line 2, after "irradiating" insert --with--;

line 6, change "provided to" to --of--;

line 7, after "and" insert --,--;

line 15, delete "the";

change "by" to --of--;

line 17, change "miniaturize" to --miniaturizes--;

line 18, change "lamination" to --laminations--;

line 24, delete "the";

change "by" to --of--;

Page 8, line 18, change "according to the" to --using a--;

line 19, change "photo" to --photolithographic--.

IN THE CLAIMS

1. (Amended) A method of producing a multi-layered wiring board comprising [the steps of]:

forming an insulating layer [made] of a photosensitive resin on a substrate for forming multi-layered wiring, and exposing and developing said insulating layer to form holes having a [predetermined shape] size;

depositing a curable resin onto said insulating layer having [said] the holes [formed therein in such a manner as to bury said] and filling the holes, and heating said curable resin to form a cured thin film of said curable resin on [the surface of] said insulating layer; and

removing said curable resin [in such a manner as to leave], leaving said cured thin film and [to form] via-holes having a [reduced opening] size reduced by said cured thin film from the size of the holes.

2. (Amended) [A] The method of producing a multi-layered wiring board according to claim 1, wherein said photosensitive resin is at least one member selected from the group consisting of an epoxy resin, an epoxy-modified acrylate resin, a cationic polymerization product of an epoxy resin, a

In re Appln. of Toyoshima et al.
Application No. Unassigned

phenol resin, a melamine resin, a carboxy-modified epoxy acrylate, and a cinnamate.

3. (Amended) [A] The method of producing a multi-layered wiring board according to claim 1, wherein said curable resin comprises one of a water-soluble resin [or] and a water-soluble cross-linking agent.

4. (Amended) [A] The method of producing a multi-layered wiring board according to claim 1, wherein said curable resin is at least one member selected from the group consisting of polymethylsiliceous siloxane, a melamine resin, an acrylate resin, and an epoxy resin.

5. (Amended) [A] The method of producing a multi-layered wiring board according to claim 1, wherein said curable resin contains rubber particles consisting of a butadiene-acrylonitrile copolymer, and [said method further comprises the step of] including chemically surface-roughening said cured thin film.

In re Appln. of Toyoshima et al.
Application No. Unassigned

6. (Amended) [A] The method of producing a multi-layered wiring board according to claim 2, wherein said curable resin comprises one of a water-soluble resin [or] and a water-soluble cross-linking agent.

7. (Amended) [A] The method of producing a multi-layered wiring board according to claim 2, wherein said curable resin is at least one member selected from the group consisting of polymethylsiliceous siloxane, a melamine resin, an acrylate resin, and an epoxy resin.

8. (Amended) [A] The method of producing a multi-layered wiring board according to claim 3, wherein said curable resin contains particles of one of calcium carbonate [or] and polybutadiene rubber.

9. (Amended) [A] The method of producing a multi-layered wiring board according to claim 4, wherein said curable resin contains particles of one of calcium carbonate [or] and polybutadiene rubber.

In re Appln. of Toyoshima et al.
Application No. Unassigned

10. (Amended) [A] The method of producing a multi-layered wiring board including a plurality of stages of via-holes formed by repeating [said] the process [steps] of claim 1, wherein [said] the via-holes of upper stages [are so formed as to possess a greater degree of reduction] are more reduced in size than [said] the via-holes of lower stages.

IN THE ABSTRACT


Please replace the existing Abstract of the Disclosure with the appended Abstract of the Disclosure.

REMARKS

The foregoing changes are made to improve the form of the patent application. No new matter has been added and entry is respectfully requested.

Table 1. Demographic characteristics of the study population	
Age (years)	65.5 (SD 10.5)
Gender	
Male	55 (42.5%)
Female	75 (57.5%)
Marital status	
Married	65 (50.0%)
Single	15 (11.5%)
Widowed	40 (30.8%)
Divorced	10 (7.7%)
Education level	
High school or less	45 (34.6%)
College or more	75 (57.4%)
Income (US\$)	
<10,000	15 (11.5%)
10,000-20,000	35 (27.0%)
20,000-30,000	40 (30.8%)
>30,000	45 (34.6%)
Health insurance	
Medicare	65 (50.0%)
Private	15 (11.5%)
Medicaid	40 (30.8%)
None	10 (7.7%)
Comorbidities	
Hypertension	45 (34.6%)
Diabetes	35 (27.0%)
Heart disease	40 (30.8%)
Stroke	15 (11.5%)
Chronic kidney disease	10 (7.7%)
Chronic lung disease	15 (11.5%)
Chronic liver disease	10 (7.7%)
Chronic pain	20 (15.4%)
Depression	15 (11.5%)
Alcohol use	
None	15 (11.5%)
Light	35 (27.0%)
Heavy	40 (30.8%)
Smoking status	
Never	45 (34.6%)
Former	35 (27.0%)
Current	40 (30.8%)
Physical activity	
None	15 (11.5%)
Light	35 (27.0%)
Heavy	40 (30.8%)
Functional status	
Independent	65 (50.0%)
Dependent	15 (11.5%)
Quality of life	
High	45 (34.6%)
Low	35 (27.0%)
Health status	
Good	45 (34.6%)
Fair	35 (27.0%)
Poor	40 (30.8%)
Very poor	10 (7.7%)

Respectfully submitted,

LEYDIG, VOIT & MAYER

 Jeffrey A. Wyand,
 Registration No. 29,458

8

In re Appln. of Toyoshima et al.
Application No. Unassigned

ABSTRACT OF THE DISCLOSURE

A method of producing a multi-layered wiring board includes exposing and developing a photosensitive resin to form holes having a size; depositing and forming a curable resin on the insulating layer, filling the holes and heating to form a cured thin film of the curable resin on the insulating layer; and removing the curable resin, leaving the cured thin film and producing via-holes having an opening reduced in size from the size of the holes by the cured thin film.